

# **Application Note: SY8113C1**

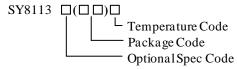
High Efficiency, 1.2MHz, 3.0A, 18V Input **Synchronous Step Down Regulator** 

## **General Description**

The SY8113C1 is a high efficiency, 1.2MHz synchronous step-down DC/DC regulator capable of delivering up to 3A load current. It can operate over a wide input voltage range from 4.2V to 18V and integrate main switch and synchronous switch with very low R<sub>DS(ON)</sub> to minimize the conduction loss.

The SY8113C1 adopts the instant PWM architecture to achieve fast transient responses for high step down applications and high efficiency at light loads. In addition, it operates at pseudo-constant frequency of 1.2MHz to minimize the size of the inductor and the capacitor.

## **Ordering Information**



Ordering Number	Package type	Note
SY8113C1ADC	TSOT23-6	

### **Features**

- Low R<sub>DS(ON)</sub> for Internal Switches (Top/Bottom):  $80m\Omega/40m\Omega$
- 4.2-18V Input Voltage Range
- 3A Output Current Capability
- 1.2MHz Switching Frequency Minimize the **External Components**
- Stable with 10µF C<sub>OUT</sub> and 0.68µH Inductor
- Instant PWM Architecture to Achieve Fast Transient Responses
- Internal Soft-start Limits the Inrush Current
- Cycle-by-cycle Peak/Valley Current Limitation
- Hic-cup Mode Output Short Circuit Protection
- Thermal Shutdown with Auto Recovery
- Output Auto Discharge Function
- Compact Package: TSOT23-6

## **Applications**

- Set Top Box
- Portable TV
- DSL Modem
- LCD TV
- IP CAM
- Networking

## **Typical Application**

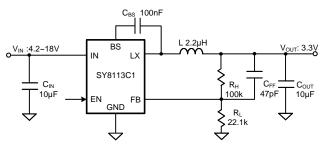


Figure 1. Schematic Diagram

Inductor and Cout Selection Table

$V_{OUT}$	L	C <sub>OUT</sub> [µF]			
[V]	[µH]	4.7	10	22	
1.2	0.68		٧	٧	
1.2	1.0		☆	٧	
2.2	1.0		٧	٧	
3.3	2.2		☆	٧	
5	1.0		٧	٧	
3	2.2		☆	٧	

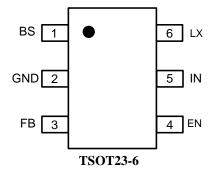
Note: '☆' means recommended for most applications.



Figure 2. Efficiency vs. Load Current



# Pinout (top view)



Top mark: E7xyz (Device code: E7, x=year code, y=week code, z=lot number code)

Pin Name	Pin Number	Pin Description		
BS	1	Boot-strap pin. Supply high side gate driver. Connect a 0.1µF ceramic capacitor between the BS pin and the LX pin.		
GND	2	Power ground pin.		
FB	3	Output feedback pin. Connect this pin to the center point of the output resistor divider (as shown in Figure 1) to program the output voltage: $V_{OUT}$ =0.6×(1+R <sub>H</sub> /R <sub>L</sub> ).		
EN	4	Enable control. Pull high to turn on. Do not leave this pin floating.		
IN	5	Input pin. Decouple this pin to GND pin with at least a 10µF ceramic capacitor.		
LX	6	Inductor pin. Connect this pin to the switching node of inductor.		

# **Block Diagram**

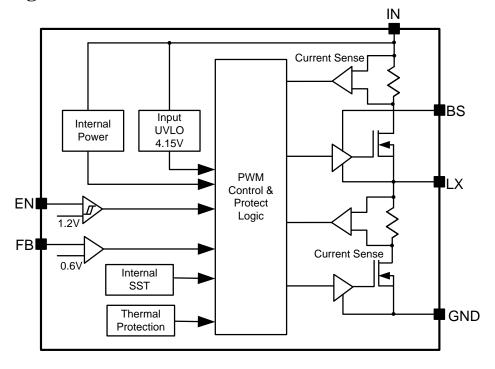


Figure 3. Block Diagram





Absolute Maximum Ratings (Note 1)	
Supply Input Voltage	0.3V to 19V
LX, EN Voltage	$-0.3V$ to $V_{IN} + 0.3V$
FB, BS-LX Voltage	0.3V to 4V
Power Dissipation, $P_D$ @ $T_A = 25^{\circ}C$ TSOT23-6	1.5W
Package Thermal Resistance (Note 2)	
$ heta_{ m JA}$	66°C/W
heta JC	
Junction Temperature Range	40°C to 150°C
Lead Temperature (Soldering, 10 sec.)	260°C
Storage Temperature Range	65°C to 150°C
Dynamic LX Voltage in 10ns Duration (Note3)	IN+3V to GND-5V
<b>Recommended Operating Conditions</b> (Note 3)	
Supply Input Voltage	
Junction Temperature Range	40°C to 125°C
Ambient Temperature Range	



## **Electrical Characteristics**

 $(V_{IN} = 12V, V_{OUT} = 3.3V, L = 2.2\mu H, C_{OUT} = 10\mu F, T_A = 25^{\circ}C, I_{OUT} = 1A \text{ unless otherwise specified})$ 

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Input Voltage Range	$V_{IN}$		4.2		18	V
Input UVLO Threshold	$V_{\rm UVLO}$				4.15	V
Input UVLO Hysteresis	$V_{HYS}$			0.6		V
Quiescent Current	$I_Q$	$I_{OUT}=0, V_{FB}=V_{REF}\times 105\%$		270		μA
Shutdown Current	$I_{SHDN}$	EN=0		5	10	μA
Feedback Reference Voltage	$V_{REF}$		591	600	609	mV
FB Input Current	$I_{FB}$	$V_{FB}=3.3V$	-50		50	nA
Output Discharge Resistance	$R_{DIS}$			40		Ω
Top FET R <sub>ON</sub>	R <sub>DS(ON)1</sub>			80		mΩ
Bottom FET R <sub>ON</sub>	R <sub>DS(ON)2</sub>			40		mΩ
EN Rising Threshold	$V_{EN,R}$		1.08	1.2	1.32	V
EN Falling Threshold	$V_{EN,F}$		0.9	1.0	1.1	V
Min ON Time	t <sub>ON,MIN</sub>			70		ns
Min OFF Time	t <sub>OFF,MIN</sub>			150		ns
Turn On Delay	t <sub>ON,DLY</sub>	from EN high to LX start switching		300		μs
Soft-start Time	t <sub>SS</sub>	V <sub>OUT</sub> from 0 to 100%		1		ms
Switching Frequency	$f_{SW}$	V <sub>OUT</sub> =3.3V, CCM		1.2		MHz
Top FET Current Limit	$I_{LIM,TOP}$		4.5			A
Bottom FET Current Limit	I <sub>LIM,BOT</sub>		3			A
Output Under Voltage Protection Threshold	$V_{UVP}$			66		$%V_{REF}$
Output UVP Delay	t <sub>UVP,DLY</sub>			120		μs
UVP Hiccup ON Time	t <sub>UVP,ON</sub>			2		ms
UVP Hiccup OFF Time	t <sub>UVP,OFF</sub>			6		ms
Thermal Shutdown Temperature	$T_{SD}$			160		°C
Thermal Shutdown Hysteresis	$T_{HYS}$			20		°C

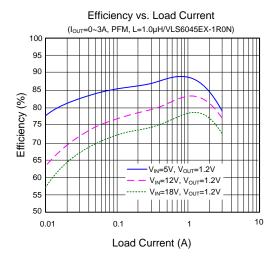
**Note 1**: Stresses beyond the "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

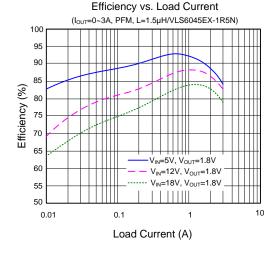
Note 2:  $\theta_{JA}$  is measured in the natural convection at  $T_A = 25$ °C on a 2-oz two-layer Silergy evaluation board. Paddle of TSOT23-6 package is the case position for SY8113C1  $\theta_{JC}$  measurement.

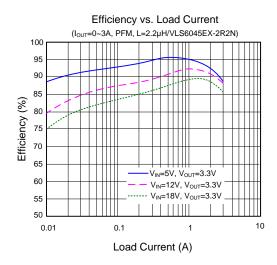
**Note 3:** The device is not guaranteed to function outside its operating conditions.

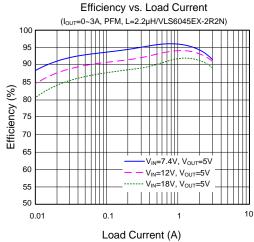


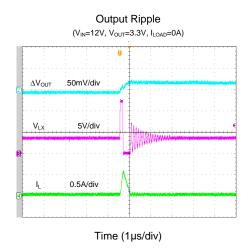
# **Typical Performance Characteristics**

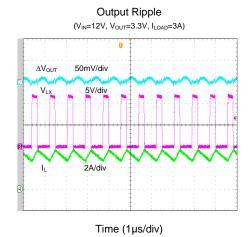




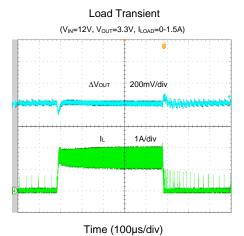


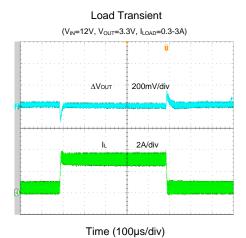


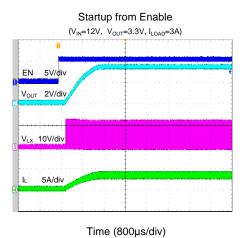


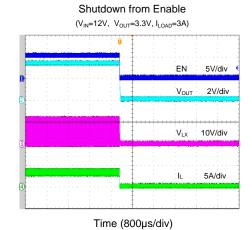


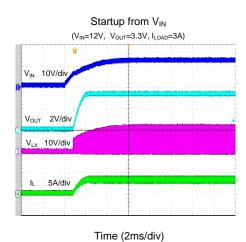


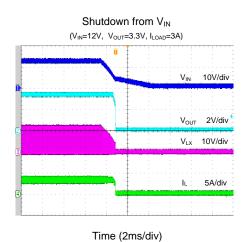






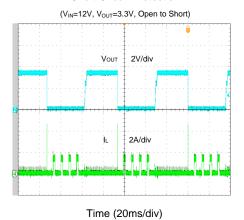




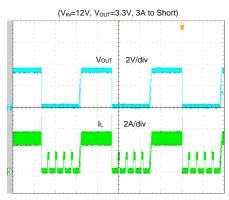




#### **Short Circuit Protection**



#### **Short Circuit Protection**



Time (20ms/div)



### **Operation**

The SY8113C1 is a high efficiency, 1.2MHz synchronous step-down DC/DC regulator capable of delivering up to 3A load current. It can operate over a wide input voltage range from 4.2V to 18V and integrate main switch and synchronous switch with very low  $R_{\rm DS(ON)}$  to minimize the conduction loss. The SY8113C1 adopts the instant PWM architecture to achieve fast transient responses for high step down applications and high efficiency at light loads.

The SY8113C1 provides protection functions such as cycle-by-cycle current limit and thermal shutdown protection. The SY8113C1 will sense the output voltage conditions for the fault protection.

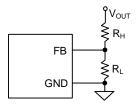
## **Applications Information**

Because of the high integration in the SY8113C1, the application circuit based on this IC is rather simple. Only the input capacitor  $C_{\rm IN}$ , the output capacitor  $C_{\rm OUT}$ , the inductor L and the feedback resistors ( $R_{\rm H}$  and  $R_{\rm L}$ ) need to be selected for the targeted applications specifications.

#### Feedback Resistor Dividers RH and RL

Choose  $R_{\rm H}$  and  $R_{\rm L}$  to program the proper output voltage. To minimize the power consumption under light loads, it is desirable to choose large resistance values for both  $R_{\rm H}$  and  $R_{\rm L}$ . A value of between  $10k\Omega$  and  $1M\Omega$  is highly recommended for both resistors. If  $V_{OUT}$  is 3.3V,  $R_{\rm H}{=}100k$  is chosen, then using the following equation,  $R_{\rm L}$  can be calculated to be 22.1k:

$$\boldsymbol{R}_{\scriptscriptstyle L} = \frac{0.6 V}{V_{\scriptscriptstyle OUT} - 0.6 V} \boldsymbol{R}_{\scriptscriptstyle H}$$



#### **Input Capacitor CIN**

The ripple current through the input capacitor is calculated as:

$$I_{\text{CIN\_RMS}} \!=\! \! I_{\text{OUT}} \! \times \! \sqrt{D \! \times \! \left(1 \text{--}D\right)}$$

Place a typical X5R or a better grade ceramic capacitor really close to the IN and GND pins to minimize the potential noise problem. Care should be taken to minimize the loop area formed by C<sub>IN</sub>, and

IN/GND pins. In this case, a  $10\mu F$  low ESR ceramic capacitor is recommended.

#### **Output Capacitor Cout**

The output capacitor is selected to handle the output ripple noise requirements. Both steady state ripple and transient requirements must be taken into consideration when selecting this capacitor. For the best performance, it is recommended to use X5R or a better grade ceramic capacitor with 16V rating and more than  $10\mu F$  capacitance.

#### **Output Inductor L**

There are several considerations in choosing this inductor.

1) Choose the inductance to provide the desired ripple current. It is suggested to choose the ripple current to be about 40% of the maximum output current. The inductance is calculated as:

$$L = \frac{V_{\text{OUT}}(1 - V_{\text{OUT}}/V_{\text{IN,MAX}})}{f_{\text{SW}} \times I_{\text{OUT,MAX}} \times 40\%}$$

Where  $f_{SW}$  is the switching frequency and  $I_{OUT,MAX}$  is the maximum load current.

The IC is quite tolerant of different ripple current amplitudes. Consequently, the final choice of the inductance can be slightly off the calculation value without significantly impacting the performance.

 The saturation current rating of the inductor must be selected to be greater than the peak inductor current under full load conditions.

$$I_{SAT, \, MIN} > I_{OUT, \, MAX} + \frac{V_{OUT}(1\text{-}V_{OUT}/V_{IN, MAX})}{2 \times f_{SW} \times L}$$

3) The DCR of the inductor and the core loss at the switching frequency must be low enough to achieve the desired efficiency requirement. It is desirable to choose an inductor with DCR<50m $\Omega$  to achieve good overall efficiency.

#### Minimum Duty Cycle and Maximum Duty Cycle

In the COT architecture, there is no limitation for small duty cycles, since even at very low duty cycles, the switching frequency can be reduced as needed once the on-time is close to the minimum on time, to always ensure a proper operation.

The device can support at least 66% maximum duty cycle operation under  $-40^{\circ}\text{C} \sim 125^{\circ}\text{C}$  condition.

In PFM light load operation, when the duty cycle is up to maximum duty cycle limitation, the device will



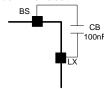
enter into CCM operation even though the load current is null.

#### Soft-start

The SY8113C1 has a built-in soft-start to control the rising rate of the output voltage and limit the input current surge during the IC start-up. The typical soft-start time is 1ms.

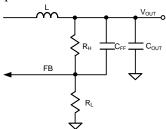
### **External Bootstrap Capacitor**

This capacitor provides the gate driver voltage for the internal high side MOSFET. A 100nF low ESR ceramic capacitor connected between the BS pin and the LX pin is recommended.



#### **Load Transient Considerations**

The SY8113C1 integrates the compensation components to achieve good stability and fast transient responses. Adding a small ceramic capacitor in parallel with R<sub>H</sub> will further speed up the load transient responses.

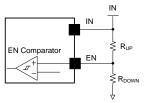


### **OCP and SCP Protection Method**

If the high side power FET current gets higher than the peak current limit threshold, the high side power FET will turn off and the low side power FET will turn on. If the low side FET current gets higher than the valley current limit threshold, the low side FET will keep turning on until low side FET current decreases below the valley current limit threshold. So both peak and valley current are limited. If the load current continues to increase in these conditions, the output voltage will drop. When the output voltage falls below 66% of the regulation level, the output short will be detected and the IC will operate in hiccup mode. The hic-cup on time will be 2ms and hiccup off time is will be 6ms. If the hard short is removed, the IC will return to normal operation.

### **Enable and Adjusting Under Voltage Lockout**

The EN pin has accurate rising and falling threshold, it provides programmable ON/OFF control by connecting an external resistor divider. Once the EN pin voltage exceeds the rising threshold, the device will start operation. If the EN pin voltage is pulled below the falling threshold, the regulator will stop switching and enter the shutdown state.



It is not recommended to connect EN and IN directly. A resistor in a range of  $1k\Omega$  to  $1M\Omega$  should be adopted if EN is pulled high by IN.

#### Lavout Design

The layout design of the SY8113C1 is relatively simple. For the best efficiency and to minimize the noise problem, the following components should be placed close to the IC:  $C_{\rm IN}$ , L,  $R_{\rm H}$  and  $R_{\rm L}$ .

- It is desirable to maximize the PCB copper area connecting to the GND pin to achieve the best thermal and noise performance. If the board space allows, a ground plane will be highly desirable.
- 2) C<sub>IN</sub> must be close to the IN and GND pins. The loop area formed by C<sub>IN</sub> and GND must be minimized.
- 3) The PCB copper area associated with the LX pin must be minimized to avoid the potential noise problem.
- 4) The components R<sub>H</sub> and R<sub>L</sub>, and the trace connected to the FB pin must NOT be adjacent to the LX net on the PCB layout to avoid the noise problem.
- 5) If the system chip interfacing with the EN pin has a high impedance state in the shutdown mode and the IN pin is connected directly to a power source such as a Li-Ion battery, it is desirable to add a pull-down  $1M\Omega$  resistor between the EN and GND pins to prevent the noise from falsely turning on the regulator.



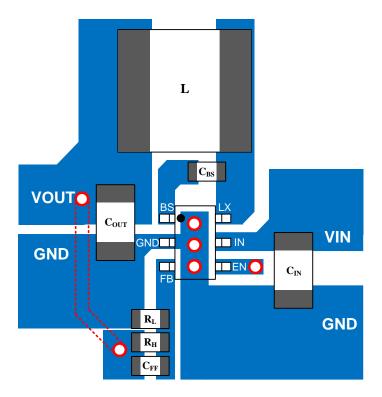
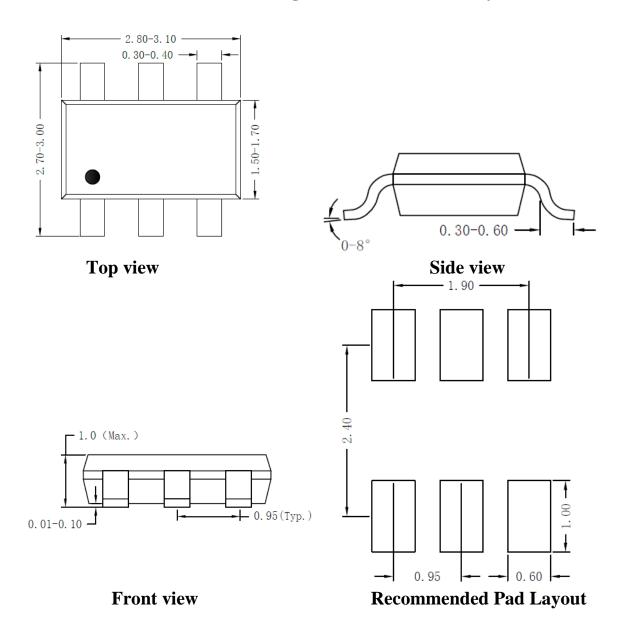


Figure 4. PCB Layout Suggestion



# TSOT23-6 Package Outline & PCB Layout



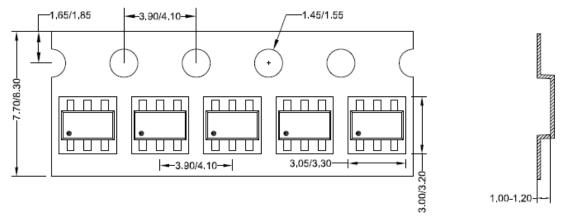
Notes: All dimension in millimeter and exclude mold flash & metal burr.



# **Taping & Reel Specification**

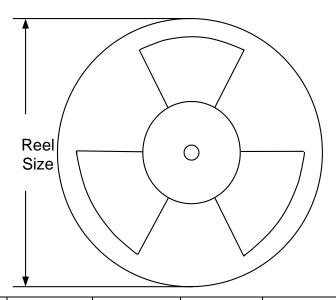
## 1. Taping orientation

### **TSOT23-6**



### Feeding direction —

### 2. Carrier Tape & Reel specification for packages



Package type	Tape width (mm)	Pocket pitch(mm)	Reel size (Inch)	Trailer length(mm)	Leader length (mm)	Qty per reel
TSOT23-6	8	4	7''	400	160	3000

### 3. Others: NA.



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